505197608 11/19/2018

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5244377

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JHIH-YANG YAN	10/23/2018
FANG-LIANG LU	10/29/2018
CHEE-WEE LIU	10/29/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.		
Street Address:	NO.8, LI-HSIN RD.6		
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK		
City:	HSINCHU		
State/Country:	TAIWAN		
Postal Code:	300		

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	16166608	

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4352521360

Email:gschneider@mabr.comCorrespondent Name:R. BURNS ISRAELSENAddress Line 1:MASCHOFF BRENNAN

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ATTORNEY DOCKET NUMBER:	T1516.10446US02	
NAME OF SUBMITTER:	TER: R. BURNS ISRAELSEN	
SIGNATURE: /R. Burns Israelsen, Reg. No. 42685/		
DATE SIGNED:	11/19/2018	

Total Attachments: 2

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PATENT 505197608 REEL: 047544 FRAME: 0715

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)				
SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME				
The PATENT RIGHTS referred to in this agreement are:				
(check one) a patent application for this invention, executed by the ASSIGNOR(S)				
concurrently with this assignment.				
☑U.S. patent application Serial No. 16/166,608 ,filed October 22, 2018				
☐ a U.S. patent application based on PCT International Application				
Nofiled on (date)(U.S. patent application				
Serial No, if known).				
U.S. patent No, issued				
The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of				
the patents and patent applications identified above.				
The PATENT RIGHTS assigned under this agreement are:				
(check one) ⊠U.S. patent rights only.				
Worldwide patent rights. In this case, the assignee shall have the right to				
claim the benefit of the filing date of any U.S. or foreign patent application				
for this invention.				
The $ASSIGNOR(S)$ referred to in this agreement is (or are) the inventor(s) whose signatures				
appear on page 2 of this Assignment and any Supplemental Sheet(s).				
The ASSIGNEE referred to in this agreement is:				
(Name of Assignee) 1.TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.				
2.NATIONAL TAIWAN UNIVERSITY				
(Address) 1.NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,				
<u>TAIWAN 300, R.O.C.</u>				
2.NO.1, SEC. 4, ROOSEVELT ROAD, TAIPEI 10617, TAIWAN, R.O.C.				
The ASSIGNEE is:				
(check one) ☐ An individual.				
A Partnership.				
1.A Corporation of TAIWAN, R.O.C.				
2. <u>A University of TAIWAN, R.O.C.</u> (specify state or country)				
other)				

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

PATENT REEL: 047544 FRAME: 0716

RECORDED: 11/19/2018



Inventor(s)-to-Assignee

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO ASSIGNEE: 1.TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. 2.NATIONAL TAIWAN UNIVERSITY

INVENTION TITLE: SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Jhih-Yang YAN	This-Yang PAN	DA18,10,23
Name of sole or first inventor	Signature 0	Date
Fang-Liang LU	Fang-Liang Lu	2018, 10, 29
Name of second inventor, if any	Fang—Liang Luc Signature	Date
Chee-Wee LIU	Chem	2018.10.29
Name of third inventor, if any	Signature	Date

PATENT REEL: 047544 FRAME: 0717